L Number	Hits	Search Text	DB	Time stamp
1	3270	257/676	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 18:58
2	13659	(semiconductor or die or chip or IC) and (align$4 or reference) near line	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 18:39
3	1868	((semiconductor or die or chip or IC) and (align$4 or reference) near line) and (mold$3 or encapsulat$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 18:42
4	1097	257/782	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 20:23
5	1		USPAT	2004/09/17 19:48
6	1	.	USPAT	2004/09/17 19:48
7	1		USPAT	2004/09/17 19:48
8	1062	257/797	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 20:46
9	1		USPAT	2004/09/17 20:29
10	1		USPAT	2004/09/17 20:30
11	1684	257/783	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 21:43
12	4690	257/787	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 22:18
13	2539	257/777	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/17 22:19